

ABSTRACT

APPARATUS AND METHOD FOR IN-MOLD DEGATING

5

An apparatus and method for degating is provided for separating excess molding material from encapsulated electronic packages while the electronic packages are located in a molding system. At least one holding device is coupled to a mold of the molding system, which is located such that excess molding material is molded onto at least a portion of the holding device during molding. A locking feature on the portion of the holding device locks the excess molding material such that the holding device may hold the excess molding material molded onto it to forcibly separate the excess molding material from the encapsulated electronic packages after molding.

10

15

(FIG. 2)